

ES3AF THRU ES3JF

Surface Mount Superfast Recovery Rectifier

Reverse Voltage – 50 to 600 V

Forward Current – 3 A

FEATURES

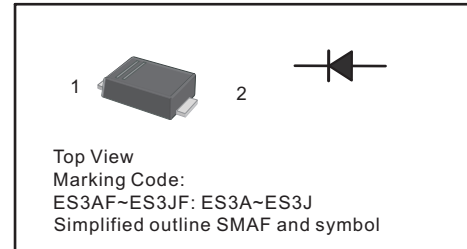
- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Superfast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

- Case: SMAF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 27mg 0.00086oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Absolute Maximum Ratings and Characteristics

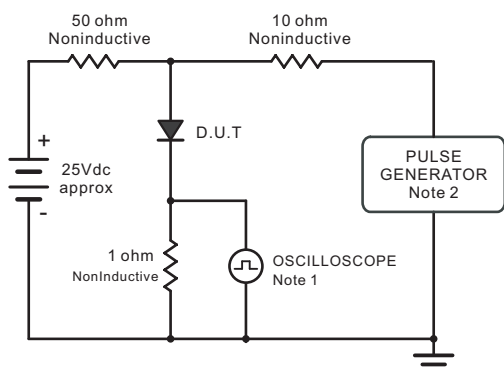
Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbols	ES3AF	ES3BF	ES3CF	ES3DF	ES3EF	ES3GF	ES3JF	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V _{RMS}	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	V _{DC}	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current at T _L = 100 °C	I _{F(AV)}	3							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	100							A
Maximum Forward Voltage at 3A	V _F	1				1.25		1.7	V
Maximum DC Reverse Current Ta = 25 °C at Rated DC Blocking Voltage Ta = 125 °C	I _R	5 200							μA
Typical Junction Capacitance at V _R =4V, f=1MHz	C _j	45							pF
Maximum Reverse Recovery Time at I _F =0.5A, I _R =1A, I _{rr} =0.25A	t _{rr}	35							ns
Operating and Storage Temperature Range	T _j , T _{stg}	-55 ~ +150							°C



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Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm, 22pF.
2. Rise Time = 10ns, max.
Source Impedance = 50 ohms.

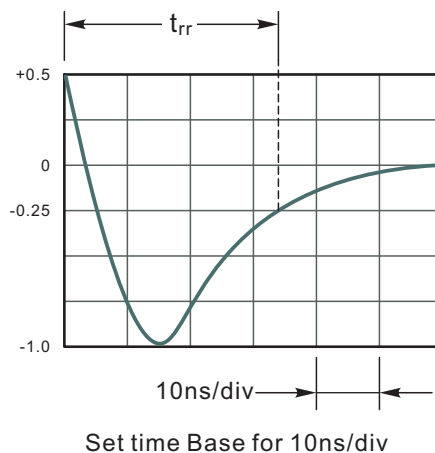


Fig.2 Maximum Average Forward Current Rating

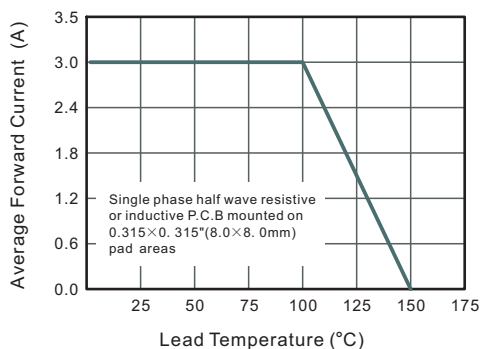


Fig.3 Typical Reverse Characteristics

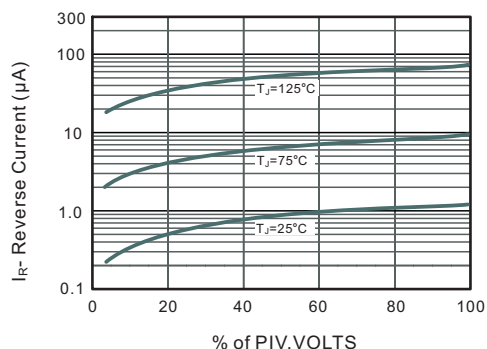


Fig.4 Typical Forward Characteristics

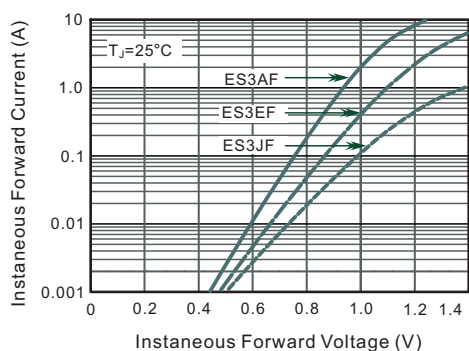
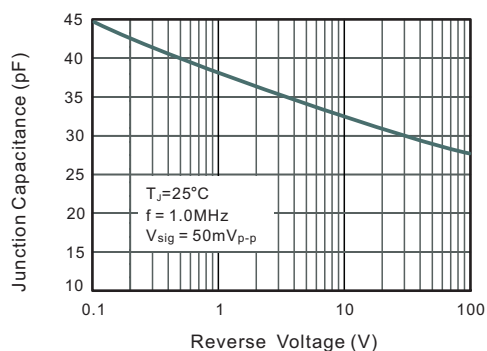
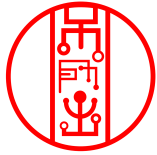


Fig.5 Typical Junction Capacitance



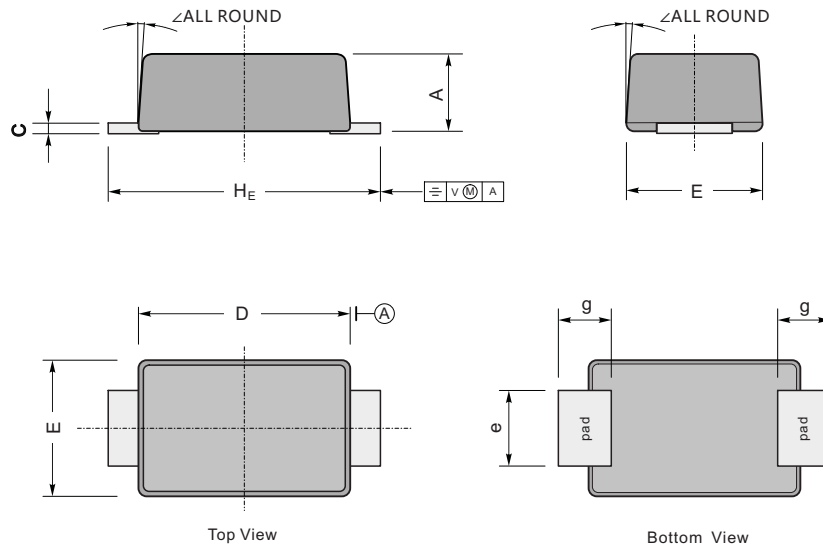


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PACKAGE OUTLINE

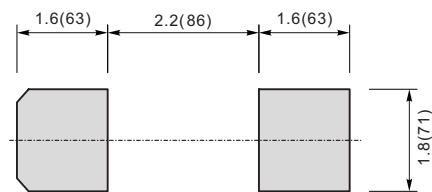
Plastic surface mounted package; 2 leads

SMAF



UNIT		A	C	D	E	e	g	H _E	∠
mm	max	1.1	0.20	3.7	2.7	1.6	1.2	4.9	7°
	min	0.9	0.12	3.3	2.4	1.3	0.8	4.4	
mil	max	43	7.9	146	106	63	47	193	
	min	35	4.7	130	94	51	31	173	

The recommended mounting pad size



Unit: mm(mil)